Amendments to the Claims:

This listing of Claims will replace all prior versions, and listings, of claims in the application where added material is shown in underlined type, deleted material is shown in ~~strikeout type~~:

Listing of Claims:

1. (Currently amended) An electromagnetic component ~~formed from a multi-layer PCB~~ comprising:

a plurality of conductive traces having a curved shape and two terminal ends, each conductive trace formed on an insulating layer ~~of said PCB~~ and positioned such that said conductive traces form a multi-layer PCB stack, wherein a first one of said conductive traces is formed on the top surface of said PCB stack and a second one of said conductive traces is formed on the bottom surface of said PCB stack;

a plurality of conductors for interconnecting the terminal ends of each said conductive trace to form at least one turn of a winding;

a first separate conductive layer attached to a first outer surface of said PCB stack in a position at the top of said PCB stack and having two terminal ends and approximately the same shape as said conductive traces;

a first additional conductor for connecting at least one of said first separate conductive layer terminal ends to a terminal end of at least one of said conductive traces;

a second separate conductive layer attached to a second outer surface of said PCB stack in a position at the bottom of said PCB stack and having two terminal ends and approximately the same shape as said conductive traces; and

a second additional conductor for connecting at least one of said second separate conductive layer terminal ends to a terminal end of at least one of said conductive traces.

2. (Currently amended) The ~~electromagnetic~~ component of Claim 1, ~~wherein a first one of said conductive traces is formed on the top surface of said PCB and a second one of said conductive traces is formed on the bottom surface of said PCB, and~~ wherein said first separate conductive layer is in conductive contact with said top conductive trace and said second separate conductive layer is in conductive contact with said bottom conductive trace.

3. (Currently amended) The component of Claim 2, wherein said first and second separate conductive layers are soldered directly onto, respectively, said top conductive trace and said bottom conductive trace.

4. (Original) The component of Claim 1, wherein each said conductive layer is a metal foil.

5. (Original) The component of Claim 1, wherein each said insulating layer defines an aperture, wherein each said conductive trace is in the shape of a loop positioned adjacent to the perimeter of a respective one of said apertures, and wherein said conductive layers are each shaped to define an aperture that corresponds to the shape of the apertures formed in said insulating layers, said component further comprising a core positioned in the space defined by said apertures.

6. (Original) The component of Claim 1, wherein the component is an inductor.

7. (Original) The component of Claim 1, wherein a plurality of conductive traces are connected by said conductors to form a first turn of said winding, and wherein at least one of said plurality of conductive traces is connected by said conductors to form a second turn of said winding.

8. (Original) The component of Claim 7, wherein said second turn of said winding includes at least two of said plurality of conductive traces.

9. (Original) The component of Claim 7, wherein at least one of said plurality of conductive traces is connected by said conductors to form a third turn of said winding.

10. (Original) The component of Claim 9, wherein said third turn of said winding includes at least two of said plurality of conductive traces.

11. (Currently amended) The ~~electromagnetic~~ component of Claim 1, wherein ~~one of said conductive traces is formed on the top surface of said PCB,~~ said electromagnetic component further ~~comprising~~ comprises an insulator disposed between said first one of said conductive

traces formed on the top surface of said PCB stack ~~top conductive trace~~ and said first separate conductive layer, wherein said insulator is separate from any other structure of said component.

12. (Currently amended) The component of Claim 11, wherein each said insulating layer defines an aperture, wherein each said conductive trace is shaped to substantially surround the perimeter of a respective one of said apertures, and wherein said first separate conductive layer and said insulator define an aperture that corresponds to the shape of the apertures formed in said insulating layers, said component further comprising a core positioned in the space defined by said apertures.

13. (Currently amended) The component of Claim 11, wherein said first separate conductive layer forms a first turn of said winding, and wherein a plurality of conductive traces are connected by said conductors to form a second turn of said winding.

14. (Original) The component of Claim 13, wherein at least one of said plurality of conductive traces is connected by said conductors to form a third turn of said winding.

15. (Original) The component of Claim 14, wherein said third turn of said winding includes at least two of said plurality of conductive traces.

16. (Original) The component of Claim 1 wherein said plurality of conductors comprise at least one plated through hole formed in each said insulating layer.

17. (Currently amended) An electromagnetic component ~~formed from a multi-layer PCB~~ comprising:

a plurality of conductive traces having a curved shape and two terminal ends, each conductive trace formed on an insulating layer ~~of said PCB~~ and positioned such that said conductive traces form a multi-layer PCB stack, and wherein a first one of said conductive traces is formed on the top surface of said PCB stack and a second one of said conductive traces is formed on the bottom surface of said PCB stack;

a plurality of conductors for interconnecting the terminal ends of each said conductive

trace to form at least one turn of a winding;

a first separate conductive layer conductively attached to said first one of said conductive traces; and

a second separate conductive layer conductively attached to said second one of said conductive traces.

18. (New) The component of Claim 4, wherein each said metal foil has a thickness that is greater than the thickness of each of said conductive traces of the multi-layer PCB stack.